

IMAPS 2010 Program Outline

Sunday, October 31

8:00 am-5:00 pm	Professional Development Courses
5:00 pm-6:00 pm	Professional Development Course Reception (Registrants and Instructors Only)

Monday, November 1

8:00 am-5:00 pm	Professional Development Courses
5:00 pm-7:30 pm	Welcome Reception (ALL ARE INVITED)

Tuesday, November 2

	3D Packaging and Integration Track	Modeling and Reliability Track	Next Generation Materials Track	Assembly and Packaging Track	Advanced Technologies Track	Interactive Track
8:00 am-11:10 am	3D Interconnect Technologies in RTP	Device Design and Modeling	Advanced Materials	Package Reliability Testing	LED Packaging	
11:00 am-5:30 pm	Exhibits Hall Open					
11:25 am-11:40 am	Annual Business Meeting					
11:40 am-12:00 pm	Awards Ceremony					
12:00 pm-12:45 pm	Keynote Presentation: Dr. John Edmond, Co-Founder, CREE Research, Inc.					
12:50 pm-1:50 pm	Lunch Kiosks (Food available for purchase)					
1:55 pm-5:40 pm	3D TSV Processes and Modeling	Design for Reliability	Ceramic and LTCC Packaging	Pb-Free Solder Materials and RoHS, Processes and Reliability	Wafer Level/CSP Packaging Requirements	

Wednesday, November 3

8:00 am-11:40 am	3D Systems Integration	Modeling and Design for Signal/Power Integrity	Thermal Management	Wire Bonding and Stud Bumping I	Emerging Technologies	
9:00 am-5:30 pm	Exhibits Hall Open					
11:45 am-12:30 pm	Keynote Presentation: Dr. Rao Tummala, Professor and Director, Georgia Institute of Technology					
12:30 pm-1:30 pm	Lunch in the Exhibits Hall					
1:35 pm-5:25 pm	3D Packaging	System-Level Signal/Power Integrity Design	High Performance Interconnects and Boards	Wire Bonding and Stud Bumping II	MEMS Packaging	Interactive Forum (Poster Session)
5:30 pm-6:30 pm	Global Business Council (GBC) Marketing Forum (INCLUDED WITH YOUR FULL SYMPOSIUM REGISTRATION)					
6:30 pm-7:30 pm	GBC Networking Reception					

Thursday, November 4

8:00 am-12:00 pm	State of 3D Technology - Consortia View	Flip Chip and Wafer Bumping: Processes and Reliability	Laminate Substrate Materials and Technology	Microwave and RF Applications	Printed and Structural Electronics	
9:00 am-12:00 pm	Exhibits Hall Open					
9:00 am-12:00 pm	IMAPS 2011 Booth Selection in the Exhibit Hall					